

# RKP201KN

## Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G1311-0200 Rev.2.00 Jan 31, 2006

### **Features**

- Adopting the trench structure minimize terminal capacitance. (C = 0.35 pF max)
- Low forward resistance. (rf =  $2.0 \Omega \text{ max}$ )
- Low operation current.
- Ultra small leadless Package (0805type; the use of an undersurface electrode structure) for use in compact and products.

### **Ordering Information**

Type No.	Laser Mark	Package Name	Package Code
RKP201KN	4	MP8	PXSN0002ZA-A

### Pin Arrangement



### **Absolute Maximum Ratings**

 $(Ta = 25^{\circ}C)$ 

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	30	V
Forward current	I <sub>F</sub>	100	mA
Power dissipation	Pd	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55 to +125	°C

### **Electrical Characteristics**

 $(Ta = 25^{\circ}C)$ 

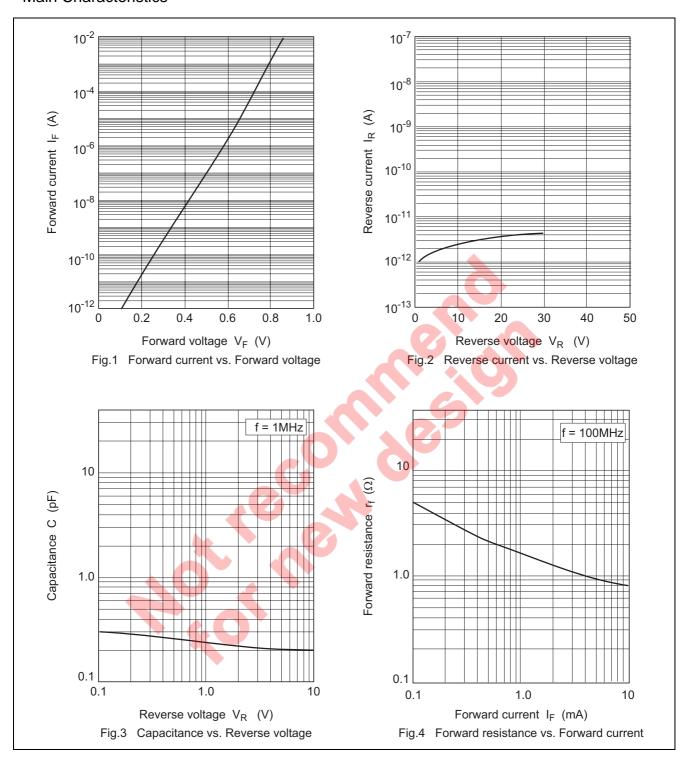
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I <sub>R</sub>	_	_	100	nA	V <sub>R</sub> = 30 V
Forward voltage	V <sub>F</sub>	_	_	0.9	V	I <sub>F</sub> = 2 mA
Capacitance	С	_	_	0.35	pF	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$
Forward resistance	r <sub>f</sub>	_	_	2.0	Ω	J <sub>F</sub> = 2 mA, f = 100 MHz
ESD-Capability *1	_	100	_	_	V	$C = 200 \text{ pF}, R = 0 \Omega$ , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ;  $I_R > 100 \text{ nA}$  at  $V_R = 30 \text{ V}$ 

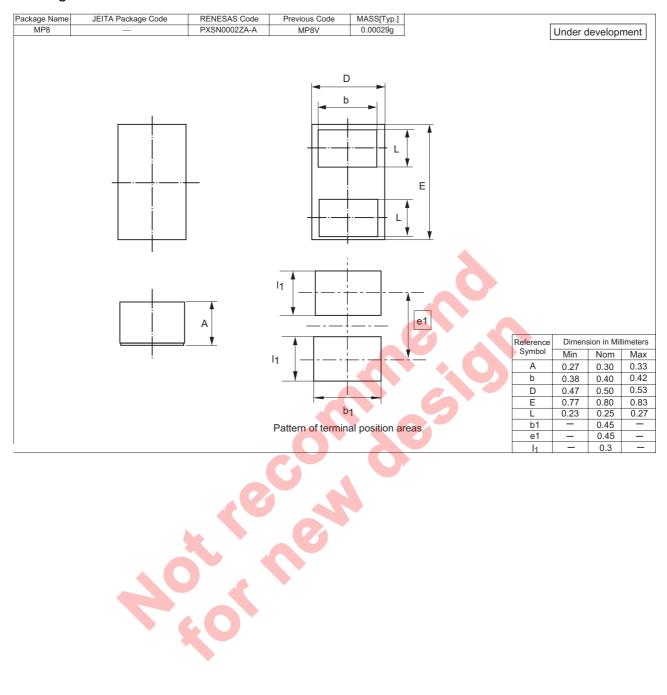
2. Please do not use the soldering iron due to avoid high stress to the MP8 package.



### Main Characteristics



### Package Dimensions



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